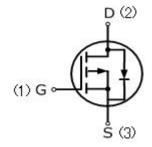


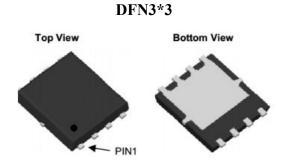
MOSFET

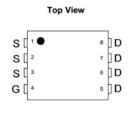
-30 Amps,-30 Volts P-CHANNEL MOSFET

FEATURE

- -30A,-30V, $R_{DS(ON)MAX}$ =15m Ω @ V_{GS} =-10V/-15A $R_{DS(ON)MAX}$ =25m Ω @ V_{GS} =-4.5V/-15A
- Low gate charge
- Low C_{iss}
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- RoHS 2.0 Compliant







Absolute Maximum Ratings (T _C =25°C,unless otherwise noted)				
Parameter	Symbol	D30P03HL	UNIT	
Drain-Source Voltage	V _{DSS}	-30	V	
Gate-Source Voltage	V_{GS}	±20	V	
Continuous Drain Current	I_D	-30		
Pulsed Drain Current(Note1)	I_{DM}	-90	A	
Single Pulse Avalanche Energy (Note 2)	Eas	151	mJ	
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55to+150	$^{\circ}$	
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	$T_{\rm L}$	260	$^{\circ}$	

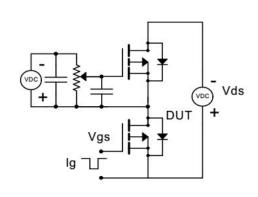
Thermal Characteristics				
Parameter		Symbol	D30P03HL	Units
Thermal resistance, Junction to Cas	e	R _{th(J-c)}	5.5	°C/W
Maximum Power Dissipation	T _C =25°C	P_{D}	22.7	W

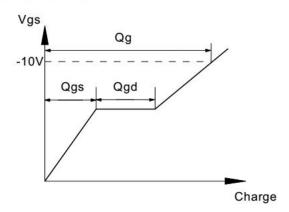
Electrical Characteristics (T _c =25°C,unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =-250uA	-30	_	_	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} =-30V, V_{GS} =0V	_	_	-1	uA
Gate-Body Leakage Current,Forward	I_{GSSF}	$V_{GS}=20V, V_{DS}=0V$	_	_	100	nA
Gate-Body Leakage Current, Reverse	I_{GSSR}	V_{GS} =-20V, V_{DS} =0V	_	_	-100	nA
On Characteristics						
Gate-Source Threshold Voltage	$V_{\text{GS(th)}}$	$V_{DS}=V_{GS}$, $I_D=-250uA$	-1.2	_	-2.5	V
Drain-Source On-State Resistance	R _{DS(on)}	V_{GS} =-10V, I_D =-15A	_	10	15	O
		V_{GS} =-4.5V, I_D =-15A	_	18	25	mΩ
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS} =-15V, V_{GS} =0V,	_	2219	_	pF
Output Capacitance	C_{oss}	f=1.0MHZ	_	310	_	pF
Reverse Transfer Capacitance	C_{rss}		_	216	_	pF
Switching Characteristics						'
Turn-On Delay Time	t _{d(on)}	V _{DD} =-15V,I _D =-15A,	_	8.6	_	ns
Turn-On Rise Time	$t_{\rm r}$	V_{GS} =-10V,	_	6.4	_	ns
Turn-Off Delay Time	$t_{d(off)}$	$R_G=2.2 \Omega$	_	46	_	ns
Turn-Off Fall Time	t_{f}		_	17	_	ns
Total Gate Charge	Qg	V _{DS} =-15V,V _{GS} =-4.5V,	_	45	_	nC
Gate-Source Charge	Qgs	$I_D = -13.9A$	_	15	_	nC
Gate-Drain Charge	Qgd		_	10	_	пC
Drain-Source Body Diode Characteristics and Maximum Ratings						
Continuous Diode Forward Current	Is		_	_	-30	A
Pulsed Diode Forward Current	I_{SM}		_	_	-90	A
Diode Forward Voltage	V_{SD}	I _S =-1A,V _{GS} =0V			-1.2	V

Notes

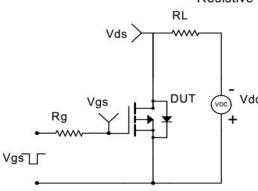
- 1. Repetitive Rating:pulse width limited by maximum junction temperature .
- 3. Pulse width≤300us;duty cycle≤2%.

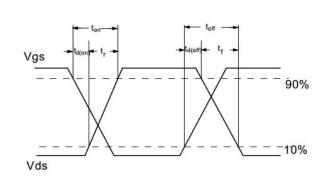
Gate Charge Test Circuit & Waveform



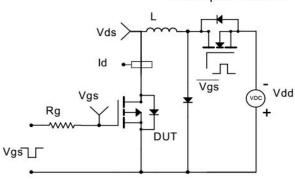


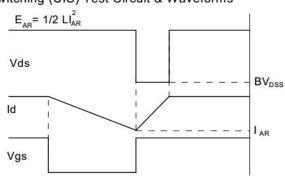
Resistive Switching Test Circuit & Waveforms



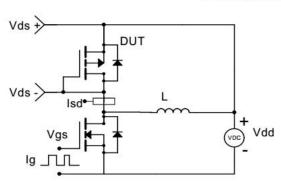


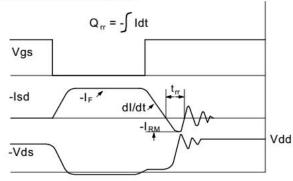
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms





RATINGAND CHARACTERISTIC CURVES

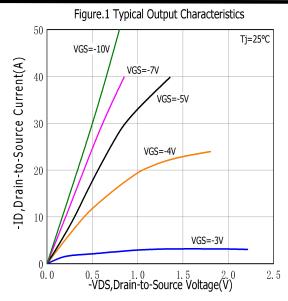


Figure.3 Typical Body Diode Transfer Characteristics

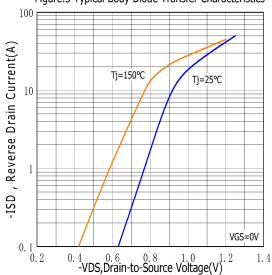


Figure.5 Typical Breakdown Voltage vs Junction Temperature

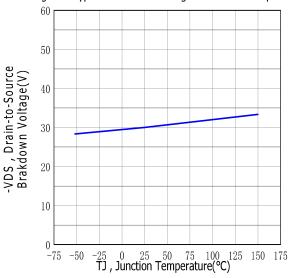


Figure.2 Typical Gate Charge vs Gate to Source Voltage

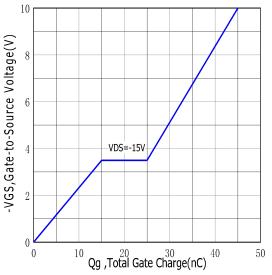


Figure.4 Typical Capacitance vs Drain to Source Voltage

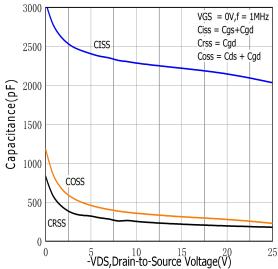
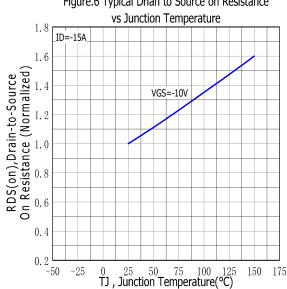
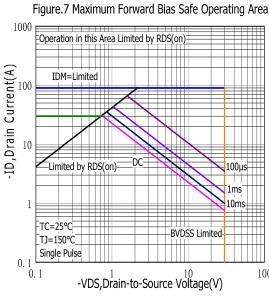
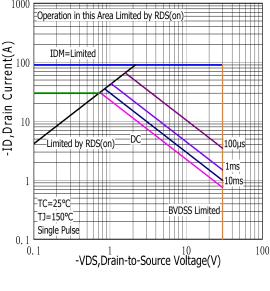
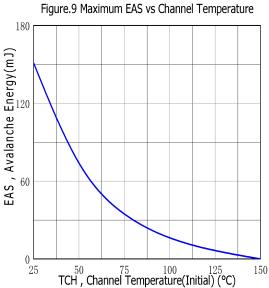


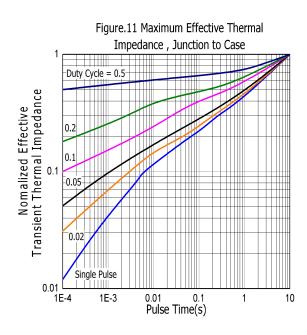
Figure.6 Typical Drian to Source on Resistance

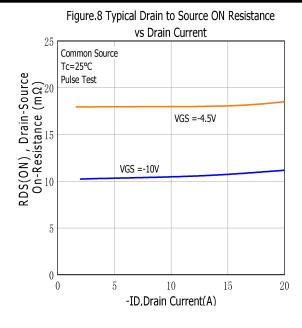


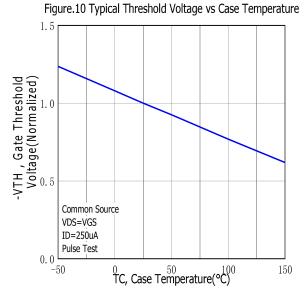


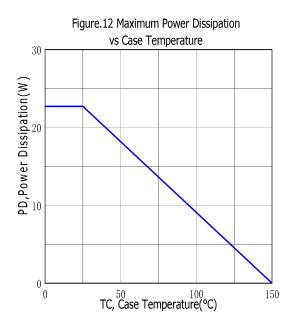




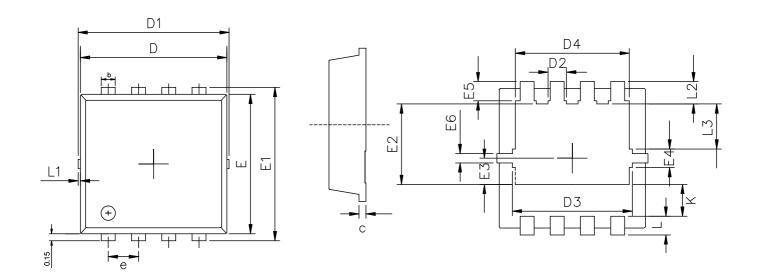


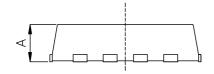




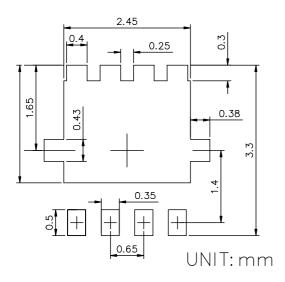


DFN3x3 PACKAGE OUTLINE





RECOMMENDED LAND PATERN



	MIN	NOM	MAX
A	0.70	0.85	1.00
b	0. 24	0.30	0.40
С	0. 10	0.15	0.25
D	3.00	3. 15	3. 25
D1	3. 10	3. 25	3.50
D2	0.30	0.40	0.50
D3	2. 50	2.58	2.70
D4	2. 35	2.45	2.55
E	2. 90	3.00	3. 10
E1	3. 15	3. 30	3. 45
E2	1.65	1.75	1.85
E3	0.48	0.58	0.68
E4	0. 23	0.40	0.50
E5	0. 20	0.30	0.40
E6	0.075	0.17	0.25
e	0.55	0.65	0.75
K	0. 52	0.72	0.82
L	0. 25	0.40	0.55
L1	0.00	0.05	0.10
L2	0. 28	0.43	0. 58
L3	0.88	0.98	1.08